



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

TSUNOI et al.

Serial Number: 09/805,559

Filed: March 14, 2001

For: MOUNTING METHOD OF SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

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TECHNOLOGY CENTER 8800
Group Art Unit 2815
Examiner: J. Nguyen

3-12-02

T. Flower
February 26, 2002

Sir:

In response to the Office Action dated October 26, 2001, extended to February 26, 2002 by a month Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Amend claims 6 and 11 to read as follows:

6. (Amended) A structure comprising:

a semiconductor device having bumps;

a board having pads so that each of the bumps is joined to a corresponding one of the pads,

each of the pads having a deformed portion with which a corresponding one of the bumps contact;

and

an insulating adhesive provided between the semiconductor device and the board, wherein

an end of each of the bumps has a diameter smaller than other portions of the bump so as to

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